

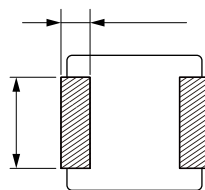
MDA HT Series

SMD Low Profile High Current Molded Inductor

Size 4020

Dimensions: [mm]

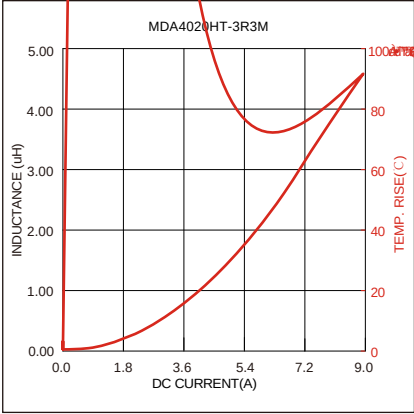
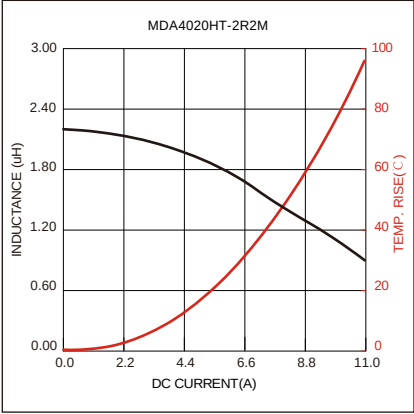
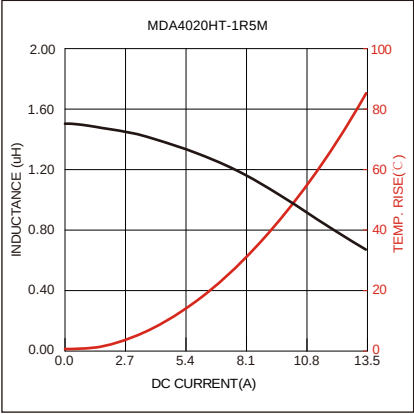
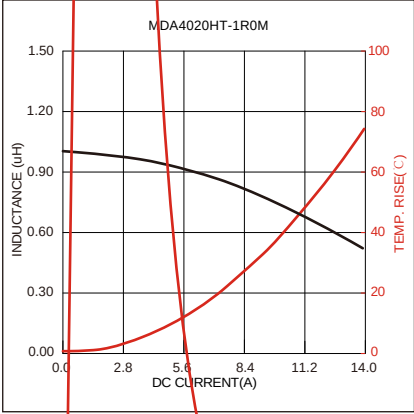
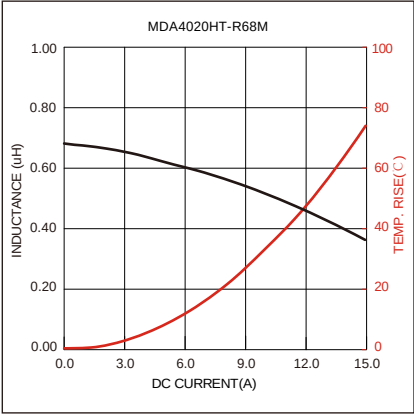
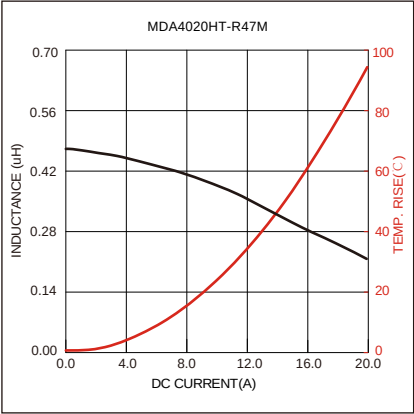
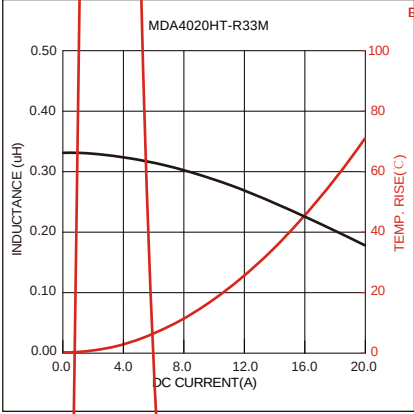
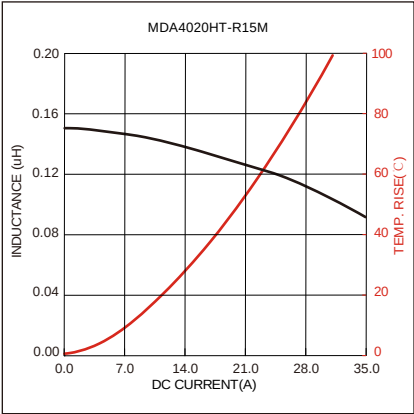
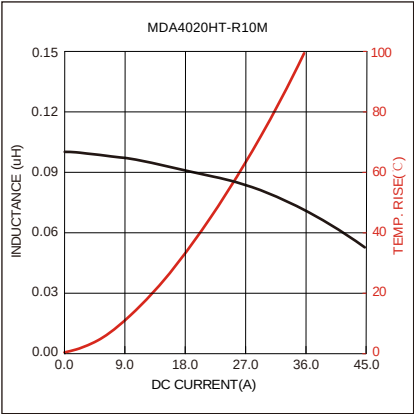
Land Pattern: [mm]

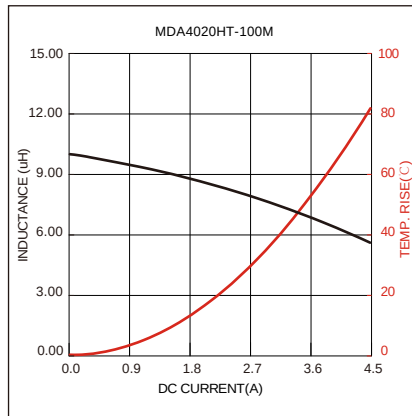
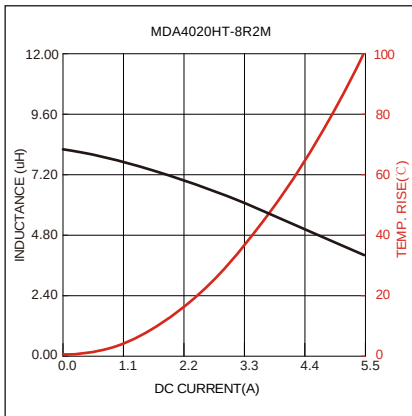
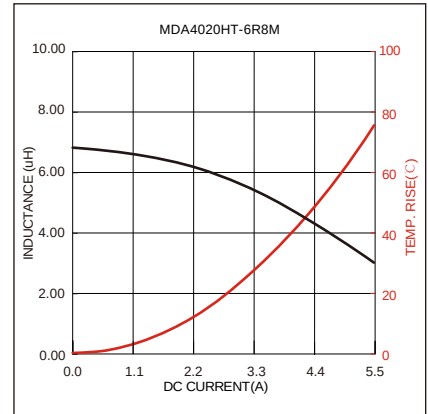
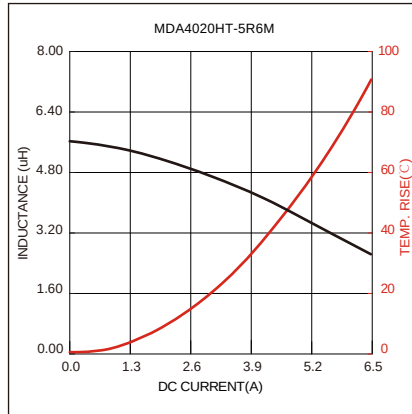
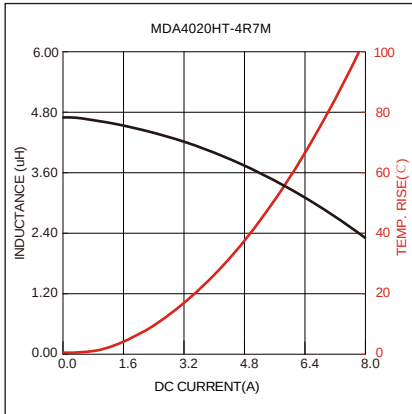


Electrical Properties:

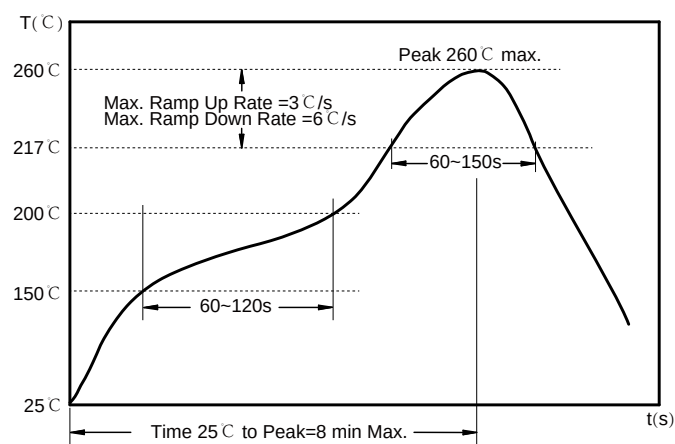
Part No	Inductance @ 1d[0@/1V	Tolerance	Temperature Rise Current Typ. (A)	Satura on Current Typ. (A)	DC Resistance Typ. (mΩ)	DC Resistance Max. (mΩ)
MDA4020HT-R10M		±20%	19.0	32.2	1.9	2.3
MDA4020HT-R15M		±20%	16.5	26.2	3.1	3.8
MDA4020HT-R33M		±20%	15.0	13.3	5.0	5.8
MDA4020HT-R47M		±20%	13.0	11.3	6.0	7.2
MDA4020HT-R68M		±20%	11.0	10.2	8.2	9.9
MDA4020HT-1R0M		±20%	10.0	10.0	11.5	13.8
MDA4020HT-1R5M		±20%	9.0	9.0	15.4	18.5
MDA4020HT-2R2M		±20%	7.2	6.4	25.0	30.0
MDA4020HT-3R3M		±20%	5.5	6.3	41.0	49.2

Typical Electrical Characteristics:





Soldering Reflow:



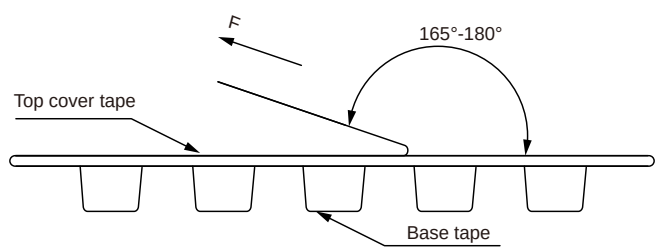
Preheat condition: 150 ~200 °C / 60~120 sec.
Allowed time above 217 °C : 60~150 sec.
Max temperature: 260 °C .
Allowed Reflow time: 3x max.

Packaging Information:

Tape Dimension :

Series	A0 (mm)	B0 (mm)
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Peel force of top cover tape:

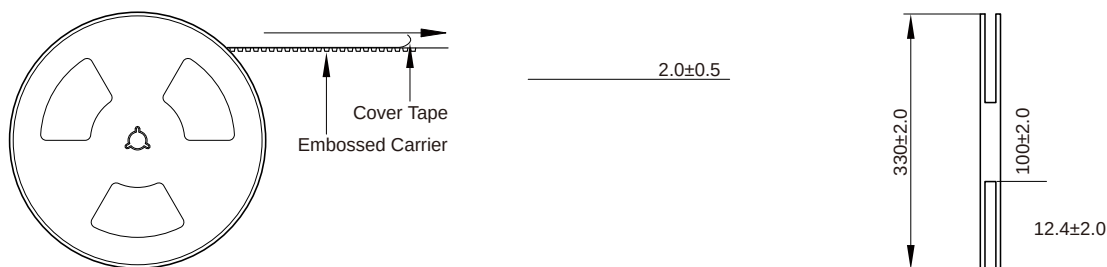


The peel force of top cover tape shall be between 0.1 to 1.3 N

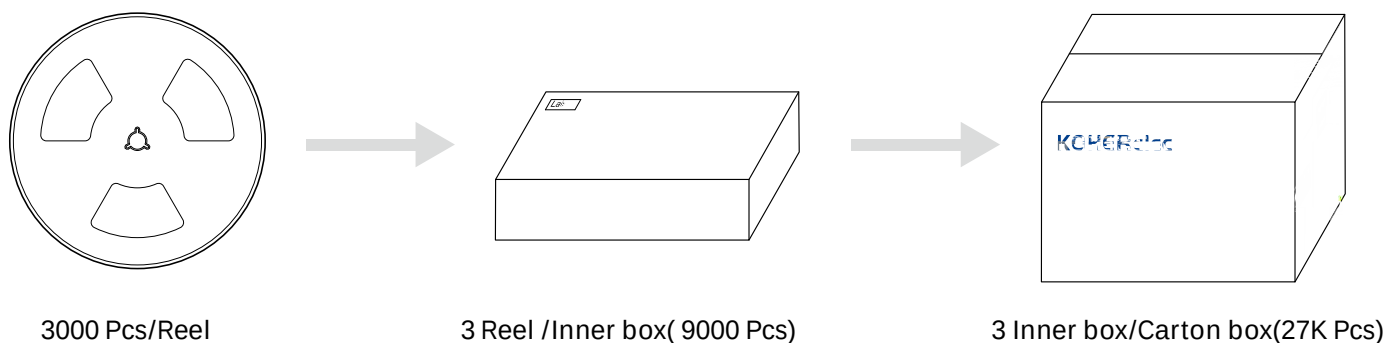
Product Marking:

Marking	Printing Inductance)
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Reel Dimension: [mm]



Packaging Quantity:



Cautions and Warnings:

Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max). If the storage period elapses, the soldering of the terminal electrodes may deteriorate. The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does. As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.